## CLAIMS

What is claimed is:

1. A method of producing a packaging substrate comprising:

providing a first precursor having a first backbone and a first ethynyl group;

providing a second precursor having a second backbone and a second ethynyl group;

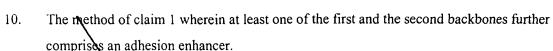
phoviding a crosslinker having at least a first and a second reactive group capable of forming a carbon-carbon bond;

applying the first precursor, the second precursor, the crosslinker and a solvent onto a surface to form an electrically insulating layer;

reacting the first ethynyl group with the first reactive group in a first carbon-carbon bond forming reaction and reacting the second ethynyl group with the second reactive group in a second carbon-carbon bond forming reaction, thereby crosslinking the first backbone with the second backbone to form the packaging substrate; and

removing the solvent.

- 2. The method of claim 1 wherein at least one of the first and second backbones comprises an aryl group.
- 3. The method of claim 2 wherein the aryl group is conjugated with the first or second ethynyl group.
- 4. The method of claim 3 wherein the avyl group comprises an arylethynyl.
- 5. The method of claim 4 wherein the arylathynyl is a phenylethynyl.
- 6. The method of claim 1 wherein the backbone comprises an indane.
- 7. The method of claim 6 wherein the indane is \$\infty\$1,3-trimethyl-3-phenylindane.
- 8. The method of claim 1 wherein the backbone comprises an oligomer.
- 9. The method of claim 8 wherein the oligomer comprises an oligo-(1,1,3-trimethylindane).



- 11. The method of claim 10 wherein the adhesion enhancer comprises a silane or siloxane group.
- 12. The method of claim 11 wherein the silane or siloxane group is selected from the group consisting of a vinyltriethoxy silane, a vinyltrimethoxy silane, a vinyltriacetoxy silane, a vinyltriacetoxy
- 13. The method of claim 1 wherein the surface comprises an organic fiber.
- 14. The method of claim 1 wherein the surface comprises a glass fiber.
- 15. The method of claim 1 wherein the first and second carbon-carbon bond forming reaction is a Diels-Alder reaction, a 4+2 cycloaddition, or a 2+2 cycloaddition.
- 16. The method of claim 1 wherein the first and second carbon-carbon bond forming reaction is a free radical reaction.
- 17. The method of claim 1 wherein the first and second carbon-carbon bond forming reaction is an Ene-reaction, a Glaser coupling, or a Straus coupling.
- 18. The method of claim 1 wherein the first precursor is evalently bound via a bridging group to the second precursor.
- 19. The method of claim 18 wherein the bridging group is an othylene, an acetylene, a divinyl benzene, or a diisopropenylbenzene.
- 20. The method of claim 18 wherein the first or second precursor comprises an indane.
- 21. The method of claim 18 wherein the backbone of the first or second backbone comprises a bromine.
- 22. The method of claim 18 wherein the first or second precursor comprises an adhesion enhancer.

23. \ The method of claim 1, further comprising:

providing a toughener; and

wherein the step of applying further comprises applying the toughener together with the first and second precursor, and the crosslinker onto a surface to form an electrically insulating layer.

- 24. The method of claim 21 wherein the backbone comprises a phenylethynyl group.
- 25. The method of claim 21 wherein the backbone comprises an indane.
- 26. The method of claim 21 wherein the backbone comprises a bromine atom.
- 27. The method of claim \( \frac{1}{2} \)1 wherein the backbone comprises an adhesion enhancer.
- 28. The method according to any of claims 1, 16, or 25 wherein the crosslinker is selected from the group consisting of a bismaleimide/allylbisphenol, a benzocyclobutane, a bifunctional vinyl aromatic, a trifunctional vinyl aromatic, a multifunctional vinyl aromatic, and a strained cyclic aliphatic.
- 29. A precursor of the formula:

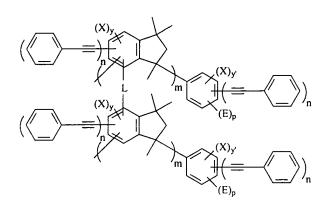
$$(X)_{y}$$

$$(X)_{y}$$

$$(E)_{p}$$

wherein X is a halogen, E is an silane or siloxane, n=1-4, y=0-3, y'=0-3 whereby y+y'>0, m=1-10, and p=0-3.

30. A precursor of the formula:



wherein X is a halogen, E is an silane or siloxane, L is an ethynyl, ethenyl, or a divinyl compound, n=1-4, y=0-3, y'=0-3 whereby y+y'>0, m=1-10, and p=0-3.

- 31. A flame retardant packaging substrate comprising:
  - a first backbone comprising a brominated indane;
  - a second backbond comprising a brominated indane;

a crosslinker covalently bound with a first bond to the first backbone and covalently bound with a second bond to the second backbone, wherein the first and the second bond are carbon-carbon bonds, respectively; and

wherein the first and second bond are formed between a reactive group of the crosslinker capable of formation of a carbon-carbon group, and an ethynyl group of the first and second backbone, respectively; and

a reinforcing dielectric material.

32. A brominated substituted indane having the structure:

$$(Br)_x$$
  
 $|$   
 $(PE)_m - (Ar)_n - R - (PE)_m$ 

wherein PE is a phenylethynyl, Ar is an indane, R is a phenyl, n = 1-20, x = 1-3, and m = 1-4.

33. A brominated substituted indane having the structure:

$$(PE)_{m} - (Ar)_{n} - R - (PE)_{m}$$

$$(PE)_{m} - (Ar)_{n} - R - (PE)_{m}$$

$$(PE)_{m} - (Ar)_{n} - R - (PE)_{m}$$

wherein PE is a phenylethynyl, Ar is an indane, R is a phenyl, B is a bridging group, n=1-10, x=1-3, p=1-20, and m=1-4.

34. A brominated substituted indane having the structure:

$$(PE)_{m} - (Ar)_{n} - R - (PE)_{m}$$

$$E$$

wherein PE is a phenylethynyl, Ar is an indane, R is a phenyl, E is an adhesion enhancer, n=1-20, x=1-3, and m=1-4.